

## N-Channel Enhancement MOSFET

### GENERAL DESCRIPTION

The ME4860 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching , and low in-line power loss are needed in a very small outline surface mount package.

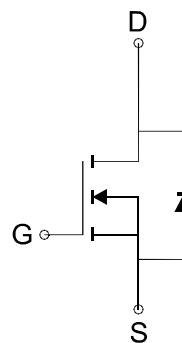
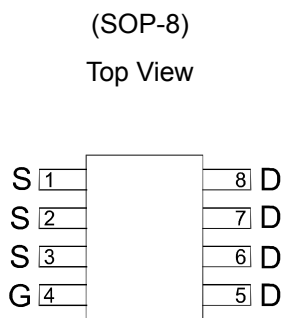
### FEATURES

- 30V/16A,  $R_{DS(ON)}=8m\Omega@V_{GS}=10V$
- 30V/15A,  $R_{DS(ON)}=11m\Omega@V_{GS}=4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

### APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

### PIN CONFIGURATION



N-Channel MOSFET

### Absolute Maximum Ratings ( $T_A=25$ Unless Otherwise Noted)

Parameter		Symbol	10 secs	Steady State	Unit
Drain-Source Voltage		$V_{DSS}$	30		V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$		V
Continuous Drain Current (t <sub>J</sub> =150 )	$T_A=25$	$I_D$	16	11	A
	$T_A=70$		13	8	
Pulsed Drain Current		$I_{DM}$	40		A
Continuous Source Current (Diode Conduction)		$I_S$	3.0	1.4	A
Maximum Power Dissipation	$T_A=25$	$P_D$	3.5	1.6	W
	$T_A=70$		2.2	1.0	
Operating Junction Temperature		$T_J$	-55 to 150		
Thermal Resistance-Junction to Ambient		$R_{\theta JA}$	67	80	/W

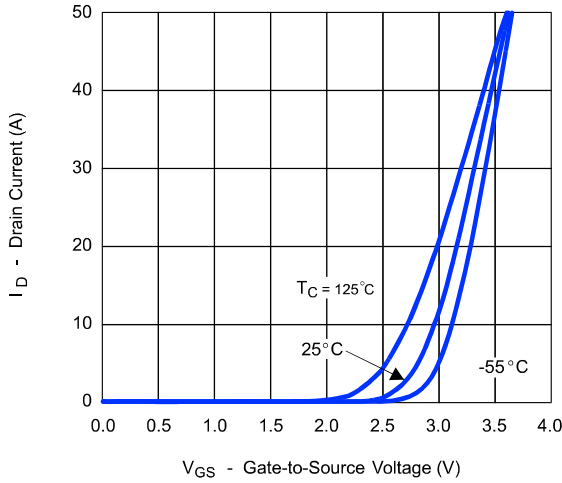
## N-Channel Enhancement MOSFET

Electrical Characteristics (T<sub>A</sub> = 25 Unless Otherwise Specified)

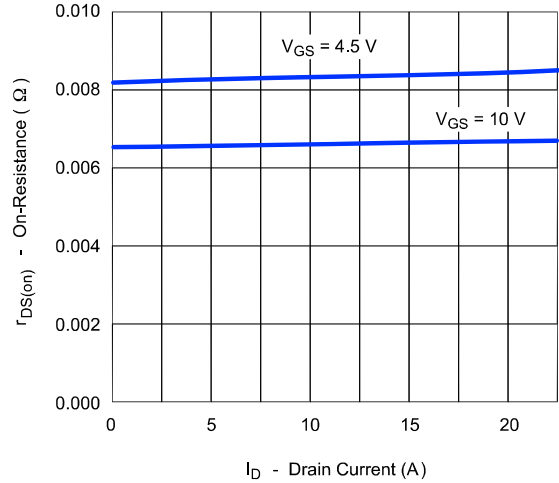
Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250 μA	30			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1.0		3.0	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V			1	μA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V			5	
		T <sub>J</sub> =70				
I <sub>D(ON)</sub>	On-State Drain Current	V <sub>DS</sub> = 5V, V <sub>GS</sub> = 10V	40			A
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> = 16A		6.6	8	m
		V <sub>GS</sub> =4.5V, I <sub>D</sub> = 15A		9	11	
G <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =15V, I <sub>D</sub> =16A		60		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =3A, V <sub>GS</sub> =0V		0.70	1.1	V
<b>DYNAMIC</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =16A		20	25	nC
Q <sub>gs</sub>	Gate-Source Charge			8		
Q <sub>gd</sub>	Gate-Drain Charge			12		
R <sub>g</sub>	Gate Resistance	F=1MHz	1.3	2.2	3.5	
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =15V, R <sub>L</sub> =15 I <sub>D</sub> =1A, V <sub>GEN</sub> =10V		18	27	ns
t <sub>r</sub>				13	18	
t <sub>d(off)</sub>	Turn-Off Time	R <sub>G</sub> =6		68	85	
t <sub>f</sub>				12	30	

## Typical Characteristics (T<sub>J</sub> = 25 °C Noted)

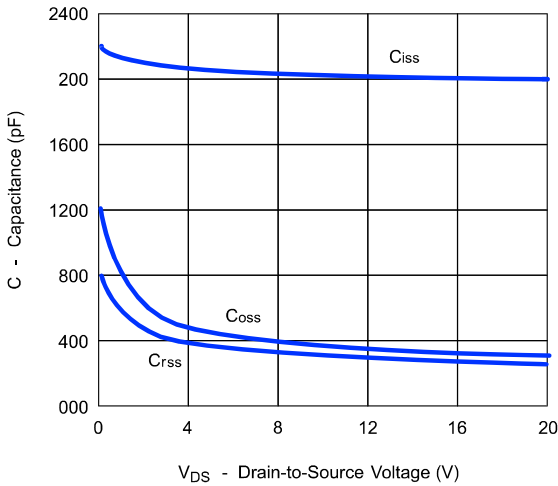
Transfer Characteristics



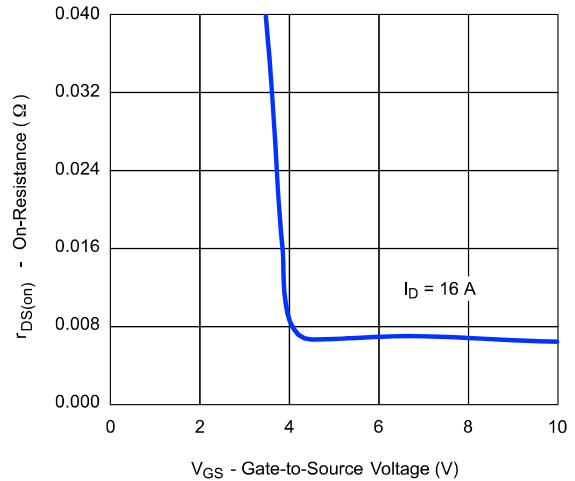
On-Resistance vs. Drain Current



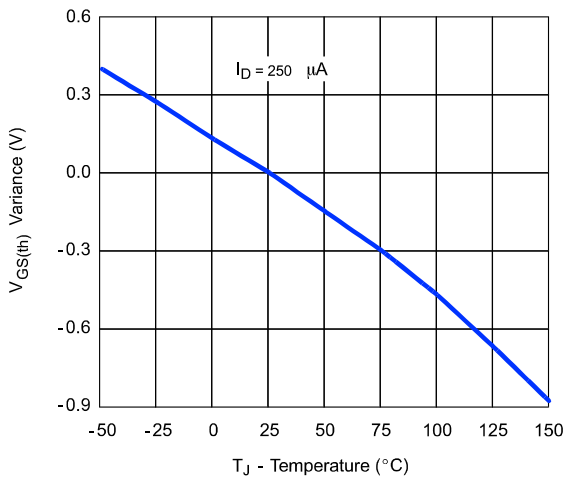
Capacitance



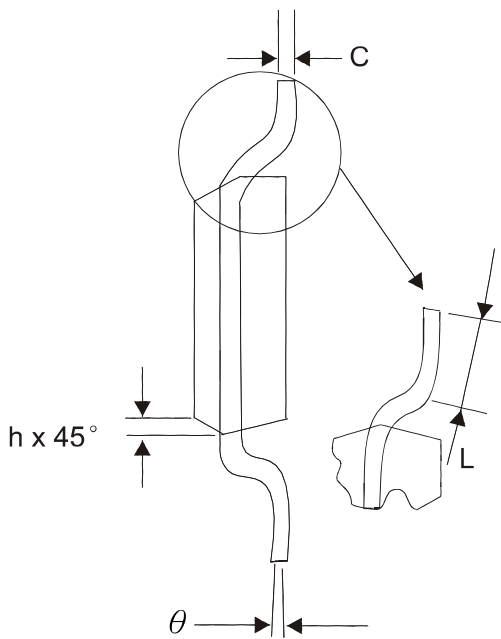
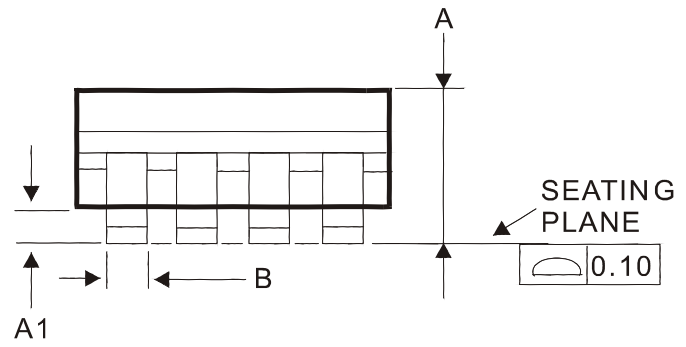
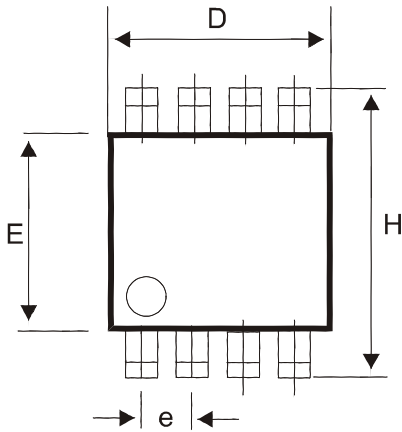
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



**SOP-8 Package Outline**



DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
	0°	7°